

**TRADEMARK ASSIGNMENT**

Electronic Version v1.1  
 Stylesheet Version v1.1

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	Grant of Security Interest in Patents and Trademarks

**CONVEYING PARTY DATA**

Name	Formerly	Execution Date	Entity Type
Micro Component Technology, Inc.		03/29/2007	CORPORATION: MINNESOTA

**RECEIVING PARTY DATA**

<b>Name:</b>	Laurus Master Fund, Ltd.
<b>Street Address:</b>	335 Madison Ave., 10th Floor
<b>Internal Address:</b>	c/o Laurus Capital Management, LLC
<b>City:</b>	New York
<b>State/Country:</b>	NEW YORK
<b>Postal Code:</b>	10017
<b>Entity Type:</b>	COMPANY: CAYMAN ISLANDS

**PROPERTY NUMBERS Total: 6**

Property Type	Number	Word Mark
Registration Number:	2655429	TAPESTRY
Registration Number:	2703499	SMARTTRAK
Registration Number:	2705844	SMARTMARK
Registration Number:	2705843	SMARTSORT
Registration Number:	1514458	MCT 3120
Registration Number:	1118129	MCT

**CORRESPONDENCE DATA**

Fax Number: (202)756-9299  
*Correspondence will be sent via US Mail when the fax attempt is unsuccessful.*  
 Phone: 8002210770  
 Email: matthew.mayer@thomson.com  
 Correspondent Name: Corporation Service Company  
 Address Line 1: 1133 Avenue of the Americas  
 Address Line 2: Suite 3100

CH \$165.00 2655429

Address Line 4: New York, NEW YORK 10036

ATTORNEY DOCKET NUMBER:

CSC # 886643

NAME OF SUBMITTER:

Matthew Mayer

Signature:

/Matthew Mayer/

Date:

05/09/2007

Total Attachments: 11

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(Trademarks)

**GRANT OF SECURITY INTEREST  
IN PATENTS AND TRADEMARKS**

THIS GRANT OF SECURITY INTEREST ("Grant"), effected as of March 29, 2007, is executed by Micro Component Technology, Inc., a Minnesota corporation (the "Grantor"), in favor of Laurus Master Fund, Ltd. (the "Secured Party").

A. Pursuant to a Master Security Agreement dated as of February 17, 2006 (as amended, restated, ratified, reaffirmed, supplemented and/or otherwise modified from time to time, the "Security Agreement") among the Grantor, certain other Assignors (as defined in the Security Agreement), and the Secured Party, the terms and provisions of which are hereby incorporated herein as if fully set forth herein, the Grantor and the other Assignors have granted a security interest to the Secured Party in consideration of the Secured Party's agreement to provide financial accommodations to Grantor and certain of its subsidiaries.

B. The Grantor (1) has adopted, used and is using the trademarks reflected in the trademark registrations and trademark applications in the United States Patent and Trademark Office more particularly described on Schedule 1 annexed hereto as part hereof (the "Trademarks"), and (2) has registered or applied for registration in the United States Patent and Trademark Office of the patents more particularly described on Schedule 2 annexed hereto as part hereof (the "Patents").

C. The Grantor wishes to confirm its grant to the Secured Party of a security interest in all right, title and interest of the Grantor in and to the Trademarks and Patents, and all proceeds thereof, together with the business as well as the goodwill of the business symbolized by, or related or pertaining to, the Trademarks, and the customer lists and records related to the Trademarks and Patents and all causes of action which may exist by reason of infringement of any of the Trademarks and Patents (collectively, the "T&P Collateral"), to secure the payment, performance and observance of the Obligations (as that term is defined in the Security Agreement).

NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby acknowledged:

1. The Grantor does hereby further grant to the Secured Party a security interest in the T&P Collateral to secure the full and prompt payment, performance and observance of the Obligations.

2. The Grantor agrees to perform, so long as the Security Agreement is in effect, all acts deemed necessary or desirable by the Secured Party to permit and assist it, at the Grantor's expense, in obtaining and enforcing the Trademarks and Patents in any and all countries. Such acts may include, but are not limited to, execution of documents and assistance or cooperation in legal proceedings. The Grantor hereby appoints the Secured Party as the Grantor's attorney-in-fact to execute and file any and all agreements, instruments, documents and papers as the Secured Party may determine to be necessary or desirable to evidence the Secured Party's

security interest in the Trademarks and Patents or any other element of the T&P Collateral, all acts of such attorney-in-fact being hereby ratified and confirmed.

3. The Grantor acknowledges and affirms that the rights and remedies of the Secured Party with respect to the security interest in the T&P Collateral granted hereby are more fully set forth in the Security Agreement and the rights and remedies set forth herein are without prejudice to, and are in addition to, those set forth in the Security Agreement. In the event that any provisions of this Grant are deemed to conflict with the Security Agreement, the provisions of the Security Agreement shall govern.

4. The Grantor hereby authorizes the Secured Party to file all such financing statements or other instruments to the extent required by the Uniform Commercial Code and agrees to execute all such other documents, agreements and instruments as may be required or deemed necessary by the Secured Party, in each case for purposes of affecting or continuing Secured Party's security interest in the T&P Collateral.

*[REMAINDER OF PAGE INTENTIONALLY LEFT BLANK]*

IN WITNESS WHEREOF, the Grantor has caused this instrument to be executed as of the day and year first above written.

**MICRO COMPONENT TECHNOLOGY, INC.**

By: *[Signature]*  
Name: *Robert*  
Title: *CEO*

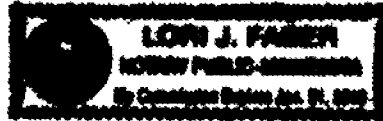
**LAURUS MASTER FUND, LTD.**

By: *[Signature]*  
Name: **Eugene Grin**  
Title: **Director**

STATE OF Minnesota )  
 ) ss.:  
COUNTY OF pine )

On this 30<sup>th</sup> day of March    , 2007, before me personally came Roger  
E. Coover who, being by me duly sworn, did state as follows: that [x]he is  
CEO of Micro Component Technology, Inc. that [x]he is authorized to execute the  
foregoing Grant on behalf of said corporation and that [x]he did so by authority of the [Board of  
Directors] of said corporation.

[Signature]  
Notary Public



STATE OF New York )  
COUNTY OF New York ) ss.:

On this 19th day of April, 2007, before me personally came Eugene Grin who, being by me duly sworn, did state as follows: that he is Director of Laurus Master Fund, Ltd. that he is authorized to execute the foregoing Grant on behalf of said company.



Notary Public

**CHRISTIAN THOMAS**  
NOTARY PUBLIC, STATE OF NEW YORK  
NO. 02TH6124424  
QUALIFIED IN NEW YORK COUNTY  
COMMISSION EXPIRES 3 / 28 / 2009

**SCHEDULE 1 TO GRANT OF SECURITY INTEREST**

**REGISTERED TRADEMARKS AND TRADEMARK APPLICATIONS**

	<u>Trademark</u>	<u>Registration or Application Number</u>	<u>Registration or Application Date</u>	<u>Country</u>	<u>Status</u>
#1	Tapestry	2,655,429	12/03/2002	USA	Registered
#2	SmartTrak	2,703,499	04/08/2003	USA	Registered
#3	SmartMark	2,705,844	04/15/2003	USA	Registered
#4	SmartSort	2,705,843	04/15/2003	USA	Registered
#5	MCT 3120	1,514,458	11/29/1988	USA	Registered
#6	MCT	1,118,129	05/15/1979	USA	Registered



**SCHEDULE 2 TO GRANT OF SECURITY INTEREST**

**PATENTS AND PATENT APPLICATIONS**

<u>Patent</u>	<u>Registration or Application Number</u>	<u>Registration or Application Date</u>	<u>Country</u>
Semiconductor Thermal Conditioning Apparatus and Method	08/972,312 U.S. Pat. No. 5,966,940	11/18/1997 10/19/1999	US
Method and Apparatus for Sorting Semiconductor Devices	09/566,458 U.S. Pat. No. 6,521,853	05/08/2000 02/18/2003	US
Method and Apparatus for Sorting Semiconductor Devices	10/308,245	12/02/2002	US
Method and Apparatus for Sorting Semiconductor Devices	[US01/14741] WO 2001/186703		PCT
Single Apparatus and Method for Manufacturing Semiconductors	60/270,073	2/20/2001	US
Single Apparatus and Method for Manufacturing Semiconductors	10/081,919	2/20/2002	US
Single Apparatus and Method for Manufacturing Semiconductors	[US02/05335] WO 2002/67300	2/20/2002	PCT
Vibratory Feeder mechanism for Device Transport	09/547,307	4/11/2000	US
Vibratory Feeder mechanism for Device Transport	10/076,061	2/13/2002	US
Method and Apparatus for Part Detection by Choked Flow	09/506,476	2/17/2000	US

Apparatus and Method for Automatically Calibrating for Temperature and Input Tray on an Integrated Circuit Handler	07/702,945 U.S. Pat. No. 5,287,294	05/20/1991 02/15/1994	US
AC Parametric Circuit Having Adjustable Delay Lock Hoop	06/526,551 4,527,126	08/26/1983 07/02/1985	US
Transmission Line Connector and Contact Set Assembly for Test Site	06/270,709 U.S. Pat. No. 4,574,235	06/05/1981 03/04/1986	US
Apparatus for Determining the Alignment of Leads on a Body	06/592,759 U.S. Pat. No. 4,553,843	03/26/1984 11/19/1985	US
Integrated Circuit Handler Heating and Singulation Apparatus	06/688,027 U.S. Pat. No. 4,579,527	12/31/1984 04/01/1986	US
Integrated Circuit Device Shuttle Construction	60227080	10/14/1985	Japan
Shuttle Actuated Singulation Apparatus	JP 62-83105 JP patent 63- 022426	04/06/1987 1/29/1988	Japan
Shuttle Actuated Singulation Apparatus	06/849,200	04/07/1986	US
Shuttle Actuated Singulation Apparatus	07/051,257 U.S. Pat. No. 4,813,573	05/13/1987 03/21/1989	US
Decoupling Apparatus for Use with Integrated Circuit Tester	06/732,968	5/13/1985	US
Decoupling Apparatus for Use with Integrated Circuit Tester	07/041,683	04/23/1987	US
Decoupling Apparatus for Use with Integrated Circuit Tester	07/145,668 U.S. Pat. No. 4,835,464	01/14/1988 05/30/1989	US

Drop Shuttle	06/772,361 U.S. Pat. No. 4,714,150	09/04/1985 12/22/1987	US
Test Site Employing Sensing Apparatus	JP 61-212544 JP patent 62- 115839	09/09/1986 5/27/1987	Japan
Centering Mechanism	06/937,838	12/04/1986	US
Centering Mechanism	07/178,842 U.S. Pat. No. 4,866,824	04/06/1988 09/19/1989	US
Impedance Matching Block	JP 62-95485 JP patent 63- 012974	04/20/1987 1/20/1988	Japan
Precision Alignment Device	JP 63-304309 JP patent 1- 288511	12/2/1988 11/20/1989	Japan
Precision Alignment Device	07/127,444 U.S. Pat. No. 4,867,296	12/02/1987 09/19/1989	US
Non-Contact High Resolution Displacement Measurement Technique	07/041,873 U.S. Pat. No. 4,827,436	04/22/1987 05/02/1989	US
Contractor for Testing Integrated Circuit chips Mounted in Molded Carrier Rings	07/703,604 U.S. Pat. No. 5,177,436	05/21/1991 01/05/1993	US
Automatic Semiconductor Part Handler	971909903	07/16/1997	China
Automatic Semiconductor Part Handler	DE19780745.3	07/16/1997	Germany
Automatic Semiconductor Part Handler	JP 10-508905 JP patent 2005- 13101	07/16/1997 10/03/2000	Japan
Automatic Semiconductor Part Handler	KR702118/98	07/16/1997	Korea
Automatic Semiconductor Part Handler	86110560 TA patent NI102192	07/24/1997 04/11/1999	Taiwan

Automatic Semiconductor Part Handler	08/678,426 U.S. Pat. No. 6,112,905	07/31/1996 09/05/2000	US
Automatic Semiconductor Part Handler	09/535,869 U.S. Pat. No. 6,234,321	03/27/2000 05/22/2001	US
Automatic Semiconductor Part Handler	[US97/12711] WO98/05059	07/16/1997 2/5/1998	PCT
Contact Set For Test Apparatus for Testing Integrated Circuit Package	06/679,911 U.S. Pat. No. 4,686,468	12/10/1984 08/11/1987	US
Disc singulator	06/750260 4818382	07/01/1985 04/04/1989	US
Soft-handling drop shuttle	06/870612 4750603	06/03/1986 06/14/1988	US
Impedance matching block	06/854331 4737116	04/21/1986 04/12/1988	US
Singulatory apparatus	06/778415 4730749	09/20/1985 03/15/1988	US
Integrated circuit placement device vacuum head	06/833104 4703965	02/25/1986 11/03/1987	US
Automatic integrated circuit transportation tube elevating and tilting device	06/750259 4647269	07/01/1985 03/03/1987	US
Integrated circuit handler automatic unload apparatus	06/808736 4645402	12/13/1985 02/24/1987	US
Integrated circuit test apparatus test head	06/381736 4517512	05/24/1982 05/14/1985	US
Integrated circuit component handler singulation apparatus	06/379892 4478352	05/19/1982 10/23/1984	US
Integrated circuit component handler movement and heating system	06/379893 4462796	05/19/1982 07/31/1984	US

Circuit package handling apparatus	06/198543 4370805	10/20/1980 02/01/1983	US
Urethral catheter puller	05/970465 4233991	12/18/1978 11/18/1980	US
Profilometry method and apparatus	05/696318 4191196		US
Nocturnal penile tumescense monitor	05/789713 4103678	04/21/1977 08/01/1978	US
Urethral profilometry catheter	05/674061 4073287	04/15/1976 02/14/1978	US
Method and aparatus for micturition analysis	05/566044 4063548	04/07/1975 12/20/1977	US
High speed magnetic core handler	05/424701 3933247		US
NOT AVAILABLE	2308245		US
Electronic component vertical stack feed apparatus for use in printed circuit assembly machines	06/573386 D290962	01/24/1984 07/21/1987	US
Combined reel feeder mounting rack and detachable feeder for use in printed circuit assembly machines	06/573385 D287020	01/24/1984 12/20/1986	US
Method and apparatus for sorting semiconductor devices	10308245	12/02/2002	US
Singulation apparatus and method for manufacturing semiconductors	10081919	02/20/2002	US